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CLAIMS

We claim:

- 1. An integrated-circuit ("IC") layout comprising a first set of vias, wherein each via in the first set has a circular shape.
- 2. The IC layout of claim 1 further comprising a second set of vias, wherein each via in the second set has a non-circular shape.
- 3. An integrated-circuit ("IC") layout comprising a first set of vias, wherein each via in the first set traverses at least two layers and has one contact on each of the layers, wherein at least one of the contacts has a circular shape.
- 4. The IC layout of claim 3, wherein each contact of each via of the first set has a circular shape.
- 5. The IC layout of claim 3 further comprising a second set of vias, each via in the second set traverses at least two layers and has one contact on each of the layers, wherein each contact of each via in the second set has a non-circular shape.
 - 6. An integrated-circuit ("IC") layout comprising:
 - a) a net with routable elements:
- b) a first set of interconnect lines for connecting the routable elements of the nets, wherein the interconnect lines have ends that are partially circular.
 - 7. The IC layout of claim 6, wherein the interconnect-line ends are semi-circular.

- 8. The IC layout of claim 6 further comprising a first set of vias that are circular.
- 9. The IC layout of claim 6 further comprising a second set of interconnect lines for connecting the routable elements of the nets, wherein the second set of interconnect lines have ends that are not partially circular.